

Description

The ZXBM5408Q is a protected H-Bridge driver designed specifically for automotive manual headlight beam control and industrial servo control applications with DC-brush motor loads. The integrated full-bridge driver output stage is composed of high-current, low-R_{DS(on)} H-bridge MOSFETs to maximize efficiency.

To simplify the circuit design and minimize external components, the device integrates voltage and temperature compensated internal references, amplifiers, and output H-bridge power switches with low $R_{DS(on)}$.

For system flexibility, the servo control forward and reverse hysteresis, deadband, and angle amplification are easily programmable by external resistors.

To help protect the motor coil, the ZXBM5408Q provides fault condition protection, such as RANGE input short to GND, short-tosupply voltage, or broken wires, by stopping the motor and disconnecting the output stage. In case of supply undervoltage and overvoltage, the device shuts down the output drive to help prevent overvoltage stress on the coil. The overcurrent protection monitors the output current and shuts down the outputs stage with periodic retry to help protect the coil from device burnout. Overtemperature shutdown provides thermal protection for the device.

The ZXBM5408Q is available in the industry standard PDIP-8 (Type A1) and SO-14 (Type A1) packages and is qualified to AEC-Q100 Grade 1 and is automotive compliant supporting PPAPs.

Features

- Servo DC Motor Drive
- Wide Operating Voltage Range: 8V to 18V
- Built-In H-Bridge with Low R_{DSON} Resistance
- Output Drive Current capability of 0.8A (Peak Current of 1.5A)
- Fault Protection—RANGE Short to GND, Supply or Broken Wires
- Overvoltage and Undervoltage Shutdown
- Overcurrent Protection
- Thermal Protection
- Green Molding in PDIP-8 (Type A1) and SO-14 (Type A1) packages
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The ZXBM5408Q is suitable for automotive applications requiring specific change control; this part is AEC-Q100 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities. <u>https://www.diodes.com/quality/productdefinitions/</u>

Pin Assignments



PDIP-8 (Type A1)



Applications

- Automotive Headlight Position Servo Motor
- 8V/12V/18V Servo DC Motors

Mechanical Data

- Moisture Sensitivity: Level 1 per JSD-020
- Terminal Finish Matte Tin Plated Leads, Solderable per JEDEC-J-STD-002.
- Weight: 0.496 grams (Approximate)
- Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
 - Lead-free.
 - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

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Typical Applications Circuit (Notes 4, 5, 6, and 7)



- Notes: 4. The C1 capacitor is for power stabilization and to strengthen the noise immunity, and the recommended value is 100nF. The capacitor is placed next to the VDD pin. The value of the capacitor can be optimized depending on the motor current. The value of C1 must be checked in the motor design in its operating conditions if reduced from the recommended value
 - 5. The C2 capacitor is for power supply filtering, and the recommended value is 47μF to 100μF. C3 is output motor noise decoupling capacitor, and the recommended value is 100nF (range of 10nF to 100nF). If strengthening OCP short function (O1 and O2 short directly), the recommended value of C2 is 10μF (range of 10μF to 20μF) for SMD type.
 - 6. The resistor values R1 and R2 define the V_{REFIN} . The resistors R_{HH} and R_{HL} define the hysteresis window.
 - 7. Diode D1 is for the reverse connection protection. The zener diode Dz is used to clamp the regenerative voltage spike from the motor operation to a safe level when reverse blocking diode D1 is used. If a reverse blocking diode is not used, the use of zener clamp Dz depends on the supply voltage capability to effectively sink the regenerative energy and voltage spike.

Pin Descriptions

1. Package Type: PDIP-8 (Type A1)

Pin Number	Pin Name	Description
1	FB	Position Feedback Input: Voltage Input
2	HYST	Hysteresis I/O
3	OUT1	Output1 Drive Sourcing & Sinking Pin
4	VDD	Power Supply Input Pin
5	OUT2	Output2 Drive Sourcing & Sinking Pin
6	GND	Ground Pin
7	RANGE	Range Input
8	REF	Reference Input

2. Package Type: SO-14 (Type A1)

Pin Number	Pin Name	Description	
1	FB	Position Feedback Input: Voltage Input	
2	HYST	Hysteresis I/O	
3, 4, 5, 10, 11, 12	GND	Ground pin	
6	O1	Output drive sourcing & sinking pin	
7	NC	No Connection	
8	VDD	Power supply input pin	
9	OUT2	Output2 drive sourcing & sinking pin	
13	RANGE	Range Input	
14	REF	Reference Input	



Functional Block Diagram



A(B) A for PDIP-8 (Type A1) B for SO-14 (Type A1)



Absolute Maximum Ratings (Note 8) @T_A = +25°C, unless otherwise specified.)

Symbol	Char	Rating	Unit	
VDD MAX	Maximum Supply Voltage (Note 9)	45	V	
Vdd_reverse Vreverse	Reverse Voltage on VDD and All Pins	-0.3	V	
Vfb_max Vhyst_max Vref_max	Maximum Voltage on FB, HYST, REF	20	V	
V _{RANGE_MAX}	Maximum Voltage on RANGE Pin		20	V
Vfb_reverse Vref_reverse Vhyst_reverse Vrange_reverse	Reverse Supply Voltage on All Pins		-0.3	V
IFB_MAX	Maximum Current on FB Pin	±6	mA	
I _{HYST_MAX}	Maximum Current on HYST Pin	±6	mA	
IREF_MAX	Maximum Current on REF Pin		±6	mA
I _{RANGE_MAX}	Maximum Current on RANGE Pin		±6	mA
D-		PDIP-8 (Type A1) (Note 11)	1.61	W
U		SO-14 (Type A1) (Note 12)	1.66	w
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TJ	Maximum Junction Temperature		+150	°C
ESD HBM	Human Body Model ESD Capability		8 (PDIP-8)	kV
CDM	Charged Device Model (CDM)		1.5 (PDIP-8)	kV

Notes: 8. Stresses greater than the *Absolute Maximum Ratings* specified above can cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.

The absolute maximum V_{DD} of 45V is a transient stress rating and is not meant as a functional operating condition. It is not recommended to operate
the device at the absolute maximum rated conditions for any period of time.

10. For thermal de-rating curves under different PCB size and layout conditions, see Thermal Performance section.

11. PDIP-8 (Type A1) soldered to minimum recommended landing pads (see *Package Outline Dimensions* section) on 2" x 2" two-layer 2oz.copper FR-4 PC (1.6mm thickness) .See *Thermal Performance* section.

12. TBD: SO-14 (Type A1) soldered to minimum recommended landing pads (see Package Outline Dimension section) on 2" x 2" two-layer 20z.copper FR4 PCB (1.6mm thickness) . See thermal performance section.

Recommended Operating Conditions

Symbol	Characteristic	Conditions	Min	Max	Unit
V _{DD}	Supply Voltage	Operating	8	18	V
T _A	Operating Ambient Temperature Range	Operating	-40	+125	°C
TJ	Operating Junction Temperature Range	Operating	-40	+150	°C



Electrical Characteristics (Note 13) (@T_A = -40°C to +125°C, V_{DD} = 8V to 18V, unless otherwise specified.)

Symbol	Characteristics	Conditions	Min	Тур	Max	Unit
I _{DD}	Supply Current (Excluding Load Current)	No Load	—	1.45	2.5	mA
VUVLO_ON	Under Voltage Protection Release Threshold	Voltage Increasing	_	7.4	8	V
V _{UVLO_OFF}	Under Voltage Protection Threshold for Shutdown to Standby Mode	Voltage Decreasing	6.3	6.9	—	V
V _{OVP_ON}	Over Voltage Protection Threshold for Shutdown to Standby Mode	Voltage Increasing	18.5	20.5	23	V
V _{OVP_OFF}	Over Voltage Release Threshold	Voltage Decreasing	17.5	20	22	V
Vон	Output Voltage High	I _{OUT} = 800mA	V _{DD} - 1.66	V _{DD} - 0.86		V
		$I_{OUT} = 500 \text{mA}$	V _{DD} – 1.05	V _{DD} - 0.54		V
Vol	Output Voltage Low	I _{OUT} = 800mA		0.56	1.12	V
		$I_{OUT} = 500 \text{mA}$		0.35	0.7	V
RON_TOTAL	Combined NMOS and PMOS R _{DSON}	$I_{OUT} = 800 \text{mA}$		1.8	3.46	Ω
Veed	REF Quiescent Voltage		185	200	215	 m\/
			100	200	7.5	1.0
KREF_IN	REF PIN Input Resistance	0 < VREF < 0.5V	4.5	6	7.5	KΩ
V _{FBQ}	FB Quiescent Voltage	$I_{FB} = 0$	185	200	215	mV
R _{FB_IN}	REF Pin Input Resistance	0 < V _{FB} < 0.5V	4.5	6	7.5	kΩ
I _{HYST_IO_250}	Current Offset	$I_{REF} = I_{FB} = 250 \mu A$, $V_{HYST} = V_{DD}/2$	-2	0.35	3	μA
I _{HYST_IO_40}		$I_{REF} = I_{FB} = 40 \mu A, V_{HYST} = V_{DD}/2$	-1.3	0	1.3	μA
V _{HYST_H} /V _S	Threshold Voltage High	—	_	52	—	%
V _{DB_H} /Vs	Deadband Voltage High	—	—	50.4	—	%
V _{DBL} /V _S	Deadband Voltage Low	—	_	49.6		%
V _{HYST_L} / V _S	Threshold Voltage Low	—	_	48	_	%
V _{HYST_W} /V _S	Hysteresis Window	(V _{HYH} – V _{HYL}) / V _{DD}	3	4	5	%
V _{DB_W} /V _S	Deadband Window	(V _{DBH} – V _{DBL}) / V _{DD}	0.4	0.8	1.2	%
I _{RANGE}	Range Pin Input Current	0V < V _{RANGE} <v<sub>DD</v<sub>	-1	—	1	μA
V _{offh}	Range Pin Input Voltage Monitor -Off Voltage High	Referred to V _{DD}	-100	0	150	mV
Voffl	Range Pin Input Voltage Monitor Switch-Off Voltage Low	Referred to GND	300	400	500	mV
IOCP	Overcurrent protection	_	1.5	—	_	Α
T _{J_SDN_TH}	IC Junction Temperature Thermal Shutdown Threshold	_	150	+170	190	°C
T _{J_SDN_HYST}	IC Junction Temperature Thermal Shutdown Hysteresis		_	+30	_	°C

Note:

 Typical data is measured at T_A = +25°C, V_{DD} = 12V. The maximum and minimum parameters values over operating temperature range are not tested in production, and they are guaranteed by design, characterization, and process control.



Operating Characteristics







Operating Characteristics (Cont.)









Application Note

REF and FB Pin

The REF and FB pins are serve AMP input, and the voltage difference between REF/FB terminals are based on the OUT1 and OUT2 operating status (like CW/CCW or Break status on page 4 and 5). For normal operating, the voltage applied to REF/FB terminals does not exceed 1.5V (= $6k \times 250\mu$ A; refer to *Electrical Characteristics* section). The two pins both have a series resistor with same value to degrade applied voltage. 1.5V is the maximum voltage at REF/FB pin, so R_{REF}/R_{FB} resistor is calculated as below:

Assuming V_{DD} = 12V and 1.5V maximum on FB/REF pin, the minimum R_{REF}/R_{FB} is equal to 1.5V= {6K / (6K + R_{REF})} × 12V; R_{REF} = 42kΩ.

HYST Pin

The hysteresis window can be set via input at HYST pin. If the two resistances R_{HYH} and R_{HYL} are equal, the hysteresis window is located symmetrically at 50 ± 2% relative to the supply voltage. The position of the window can be adjusted by varying the ratio of R_{HYH} to R_{HYL} . The size of the window tolerance can be adjusted by changing the ratio of the hysteresis resistances to the resistances R_{REF} and R_{FB} on the other. For example, if the resistances R_{HYH} and R_{HYL} are both halved in comparison to R_{REF} and R_{FB} , the window tolerance doubles in size (i.e. to 50 ± 4%).

RANGE Pin

If the potentiometer or the connecting leads reference input to V_{REF} are shorted or open connected, uncontrolled movements of the servo motor must not occur. For this reason, two additional switch-off thresholds V_{OFFL} and V_{OFFH} are provided. The corresponding window comparator for these thresholds behind the RANGE input has a typical low threshold of 0.4V and a typical high threshold of V_{DD} . If the voltage V_{REFIN} falls below 0.4V typical, which will be the case if the reference potentiometer input is shorted to ground, the motor will be switched off. Similarly, if the voltage V_{REFIN} rises above V_{DD} typical, which will be the case if the reference potentiometer input is open circuited, the motor will be switched off.

Undervoltage Lockout

To make sure the minimum voltage required to operate the driver is supplied, the ZXBM5408Q has an undervoltage lockout. At start up the device only starts if the supply voltage is typically over V_{UVLO_RLTH} . During normal operation, the device will switch off all the output switches and power down if the supply voltage drops below V_{UVLO_TH} typical.

When the supply voltage drops below undervoltage lockout threshold, V_{UVLO_TH_R}, the ZXBM5408Q shuts down all the output drive switches and enters standby mode to help prevent overvoltage stress on the coil.

Overvoltage Shutdown of Output Drive

When the supply voltage exceeds the overvoltage shutdown threshold, V_{OV_TH} , the ZXBM5408Q shuts down all the output drive switches and enters standby mode to help prevent overvoltage stress on the coil. The driver returns to normal condition if the supply voltage drops below V_{OV_RLTH} provided no other fault condition or signals are preventing it to enter normal operation.

Overcurrent Protection

The internal overcurrent protection (OCP) threshold is 1.5A minimum at 12V supply +25°C.

When the motor current exceeds the OCP threshold for longer than 4µs typical on any of the H-Bridge switches, the device switches off all the output switches and remains off for 260µs typical. The IC returns to normal operation after the 260µs if overcurrent condition has gone away. If the motor current is still higher than the OCP threshold, the device enters another 260µs standby mode.

Thermal Shutdown Protection

The device has an internal thermal shutdown to prevent a thermal runaway scenario. The thermal shutdown is triggered when the junction temperature of the device reaches +170°C. It will remain in standby mode until the junction temperature falls by +30°C.



Typical Operating Characteristics

Supply Current





UVLO and OVP Threshold





Typical Operating Characteristics (continued)

Total H-Bridge Path Resistance – Total RDS(ON) of High-Side and Low-Side Switches



0.60

0.40

0.20

-50

-25

0

25

50

Temperature (°C)

75

100

125

150

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0.60

0.40

0.20

-50

-25

0

25

50

Temperature (°C)

75

100

125

150



Typical Operating Characteristics (cont...)











Thermal Performance

(1) Package Type: PDIP-8 (Type A1)





Note: 14. PDIP-8 (Type A1) soldered to minimum recommended landing pads on 2" x 2" two-layer 2oz.copper FR-4 PCB (1.6mm thickness).

(2) Package Type: SO-14 (Type A1)

SO-14 Power Dissipation De-rating Curve 1 (Note 15)



Note: 15. The SO-14 pad is soldered to the minimum recommended landing pads (see Package Outline Dimension section) on a 2" x 2" 2oz. copper FR4 PCB (1.6mm thickness) with no copper flood connecting to the landing pattern or on the bottom layer.



Ordering Information



	Paakaga Paakaging		Tube(Note 18)		13" Tape and Reel		Compliance	
Part Number	Code	(Note 16)	Quantity	Part Number Suffix	Quantity	Part Number Suffix	(Note 17)	
ZXBM5408Q -N-U	N	PDIP-8 (Type A1)	60	-U	NA	NA	Automotive Grade Compliant	
ZXBM5408Q -S14-13 (Future Product)	S14	SO-14 (Type A1)	NA	NA	2,500/Tape & Reel	-13	Automotive Grade Compliant	

Notes: 16. Pad layout as shown on Diodes Incorporated's Suggested pad layout can be found at https://www.diodes.com/design/support/packaging.

17. ZXBM5408Q -N-U is classified as "Automotive Compliant" and supports PPAP documentation.

18 There are 60 tubes in a box and the standard order quantities is 3600 pcs.

Marking Information

1. Package Type: PDIP-8 (Type A1)



2. Package Type: SO-14 (Type A1)





Package Outline Dimensions (All dimensions in mm.)

Please see https://www.diodes.com/design/support/packaging/ for the latest version.

1. Package Type: PDIP-8 (Type A1)



PDIP-8 (Type A1)						
Dim		Inches	;	Millimeters		
Dim	Min	Max	Тур	Min	Max	Тур
Α	-	0.210	-	-	5.334	
A1	0.015			0.381		
A2	0.125	0.135	0.130	3.175	3.429	3.302
b			0.018			0.457
b2	-		0.060	-		1.524
С	0.008	0.014	0.010	0.203	0.356	0.254
D	0.355	0.400	0.365	9.017	10.160	9.271
Е	0.	300 BS	SC	7	7.62 BSC)
E1	0.245	0.255	0.250	6.223	6.477	6.350
eB	0.335	0.375	0.355	8.509	9.525	9.017
е			0.100			2.540
L	0.115	0.150	0.130	2.921	3.810	3.302
а	0°	15°	7°	0°	15°	7°
C	Controlling dimensions are in inches					

2. Package Type: SO-14 (Type A1)



SO-14 (Type A1)					
Dim	Min	Min Max Typ			
Α		1.75			
A1	0.10	0.25			
A2	1.25				
b	0.31	0.51			
С	0.10	0.25			
D		8.65 BSC			
Е		6.00 BSC			
E1		3.90 BSC			
e		1.27 BSC			
h	0.25	0.50			
L	0.40	1.27			
θ	0°	8°			
	All Di	mensions	s in mm		



Suggested Pad Layout

Please see https://www.diodes.com/design/support/packaging/ for the latest version.



Dimensions	Value (in mm)
С	1.27
C1	5.40
Х	0.60
Y	1.50



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